

**IN THE UNITED STATES PATENT & TRADEMARK OFFICE**

Appln. Ser. No.:	Filed:	Inventor(s):	Atty Dkt:
Divisional of 09/825,418	3 April 2000	Y. Awakura	114GI-135C
Title: Wiring Board with Ground Part and Comprising Granular Magnetic Film			

Asst. Comm'r for Patents  
Washington, D.C. 20231-0001

**PRELIMINARY AMENDMENT**

Dear Sir:

Prior to an examination on the merits of the subject application, please first amend the application as follows, the amendments being shown in marked-up form in the attached appendix.

**IN THE SPECIFICATION:**

Page 1, after the title and prior to the background section, add the paragraph:

This application is a divisional of application 09/825,418, filed 3 April 2001, a Convention application based on Japanese applications 101756 and 101765, both filed 4 April 2000.

**IN THE CLAIMS:**

Cancel claims 1-18.

19. (Amended.) A wiring board, comprising:
- a board of at least one layer comprising a conductor part, said conductor part comprising at least one of ground patterns or conductor patterns deployed on one surface of said board, or comprises a ground surface deployed over the entirety of one